FOR IMMEDIATE RELEASE

SUSS MicroTec's Hybrid Bonding All-Rounder XBC300 Gen2 D2W/W2W to be added to Center for Neovation Microelectronics Fabrication Facility

Semiconductor ecosystem continues to grow capabilities at NeoCity in Osceola County, Florida

CORONA, Calif., and OSCEOLA COUNTY, Fla., July 9, 2024 – SUSS MicroTec SE, a leading manufacturer of system and process solutions for the semiconductor industry, continues to strengthen its presence in Central Florida through the addition of its hybrid bonding all-rounder XBC300 Gen2 D2W/W2W to fab equipment capabilities inside the Center for Neovation located at NeoCity, a 500-acre master-planned technology district in Osceola County, Florida.

The Center for Neovation is a 109,000-square-foot microelectronics fabrication facility owned by Osceola County and operated by SkyWater Technology that is designed to be flexible and adaptable with opportunities to accommodate a variety of partner-funded semiconductor manufacturing research and development activities. Leveraged by its partnership with BRIDG—a not-for-profit, public-private partnership specializing in advanced system integration and packaging of next-generation microelectronics production process technologies—and previous tools originally acquired by Osceola County, SUSS MicroTec established a production-level application center in North America in 2019 so its North American customers can access breakthrough innovations while providing the Center for Neovation with state-of-the-art equipment ranging from advanced lithography and nano-imprinting to temporary bonding, debonding and permanent bonding.

The acquisition of this new tool was funded through an EDA Build Back Better Regional Challenge grant awarded to Osceola County and its partners, with SkyWater Technology providing a 20 percent match for the tool. The fully integrated platform enables wafer-to-wafer (W2W) as well as collective and sequential die-to-wafer (D2W) hybrid bonding to strategically expand capabilities in the field of advanced system integration and packaging. The new 200mm/300mm compatible system will primarily support state-of-the-art W2W and above all D2W requirements in the scope of public-private and government funded projects.

"The addition of SUSS MicroTec's next generation hybrid bonding cluster enables a complete range of automated bump-less assembly D2W/W2W capabilities, fulfilling our industry need for a universal heterogenous integration tool to support future product manufacturing," said Dr. John Allgair, BRIDG CTO.

Both D2W and W2W hybrid bonding have constantly grown in importance for 3D integration to address the slowdown of two-dimensional scaling associated with Moore's Law. Hybrid bonding, as an extension of conventional fusion bonding, is a key technology enabler for the future heterogeneous integration market in terms of advanced 3D device stacking, e.g. for next-generation memory or demanding SoC (System on Chip) applications.

"The addition of the universal heterogeneous integration cluster XBC300 Gen2 D2W/W2W provides our customers with a big head start in the market by making cutting-edge hybrid bonding technology available for demonstration and evaluation in a real production environment," stated Gary Choquette, General Manager SUSS MicroTec Inc.

"We look forward to adding the equipment to fab capabilities at the Center for Neovation as we continue to grow the semiconductor ecosystem in Osceola County and take advanced 3D integration to the next level," stated Jay Galbraith, president of BRIDG.

For information about the XBC300 Gen2 D2W/W2W, visit: www.suss.com/en/products-solutions/wafer-bonder/xbc300-gen2-d2w-w2w.

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About EDA Build Back Better Regional Challenge Grant
Osceola County is part of an elite group of 21 coalitions that the Biden Administration is backing to boost the nation's economic recovery and rebuild American communities. As a Build Back Better Regional Challenge Grant awardee, Osceola and its Coalition partners received $50.8 million from the U.S. Department of Commerce's Economic Development Administration (EDA) to develop Central Florida's semiconductor and microelectronics industry cluster. Out of 529 original submissions, the Osceola-led Central Florida Coalition was one of 60 finalists -- and the only one in Florida to make it to the final round. Officials from the U.S. Department of Commerce believe the local vision and detailed plan hold the opportunity to transform the Central Florida region. Funds from this award expands the Center for Neovation fabrication lab and manufacturing capabilities, creating opportunities for new jobs in the technology field.

About BRIDG
BRIDG is a not-for-profit, public-private partnership serving Osceola County, Florida in creating the semiconductor advanced packaging and workforce hub for America. As an ITAR-certified and DMEA trust-ready supplier, BRIDG offers R&D expertise in digital, RF, and photonics interposer technology development coupled with advanced packaging capabilities and a 200mm microelectronics fabrication facility geared toward system miniaturization, device integration, hardware security, and product manufacturing to produce high quality, high reliability products key to multiple market segments. BRIDG provides the physical infrastructure and collaborative process to connect challenges and opportunities with solutions, unlocking the potential of microelectronics systems technologies to positively impact customers, partners, and society. By "BRIDGing the innovation development gap" through partnerships, knowledge exchange, product manufacturing, and responsible innovation key to national security and domestic self-sufficiency, BRIDG is a catalyst for driving the microelectronics systems industry forward. Located at NeoCity, BRIDG is centrally located 20 minutes from Orlando International Airport and within a mile of Florida's Turnpike. www.GoBRIDG.com

About NeoCity
Following the impacts of the Great Recession, Osceola County decided to make a long-term investment to create a 500-acre technology district, known as NeoCity, to diversify its economy. Since then, Osceola County, and their regional partners, have invested over $273 million to make NeoCity the hub to Central Florida's burgeoning semiconductor industry. NeoCity's anchor building, the Center for Neovation, (total of 109,000 sq. ft) consisting of a 36,000 square ft. cleanroom, is home to SkyWater Technology, imec USA, BRIDG, TEL, Plug and Play Semiconductors, and SUSS MicroTec. The Osceola County School District's NeoCity Academy, located next to the Center for Neovation, works with SkyWater, BRIDG, and imec USA to provide internships for the high school students to work in the industry. www.NeoCityFL.com

About Osceola County
Osceola County is one of the fastest growing counties in the nation. It is a dynamic and innovative community focused on a vision to be the center of research and manufacturing innovation of a regional economy. Osceola is a diverse community of lifelong residents and recent transplants, third-generation immigrants and new arrivals – all who flourish here because the County's leaders are dedicated to fostering innovation, economic growth, and partnerships that benefit its residents and businesses. In the amidst approximately 7 million annual overnight guests who enjoy easy access to Central Florida's world-famous theme parks, the County's unique sights and unmatched hospitality, Osceola County leads Central Florida by example – so that its partners can always count on being first to what's next.

About SUSS MicroTec
SUSS MicroTec is a leading supplier of equipment and process solutions for microstructuring in the semiconductor industry and related markets. In close cooperation with research institutes and industry partners SUSS MicroTec contributes to the advancement of next-generation technologies such as 3D integration and nanoimprint lithography as well as key processes for MEMS and LED manufacturing. With a global infrastructure for applications and service SUSS MicroTec supports more than 8.000 installed systems worldwide. SUSS MicroTec is headquartered in Garching near Munich, Germany. The shares of SUSS MicroTec SE are traded in the Prime Standard of the German Stock Exchange (ISIN DE000A10K0235). For more information, please visit www.suss.com.